˜Y ب / Descriptions

N ێ TO-3PH ﻋ ﻣ

N-Channel MOSFET in a TO-3PH Plastic Package.

◕ Ề / Features

ﻫ Ḥ RDS(ON) Qg Ḥ ﻋ ɔ

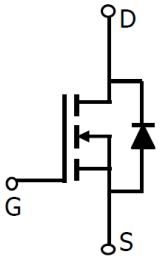
Fast Intrinsic Rectifier,Low RDS(ON) and Qg,Low Package Inductance

ﻳ ﻩ / Applications

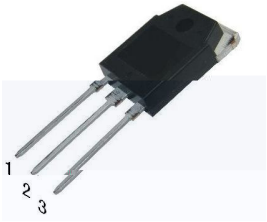
ɔ ز ɔ GF0GF ﺷ ´ ɔ ﺷ

Switch-Mode and Resonant-Mode Power Supplies,DC-DC Converters,Laser Drivers,AC and DC Motor Drives,Robotics and Servo Controls.

Ɲ ڤ ̃ ̃ ﻫ ص / Equivalent Circuit



ã ﻟ ﻳ ̃ / Pinning



PIN1 Gate PIN 2 Drain PIN 3 Source

̃ ﻳ z ﻋ ﻫ ﺷ / h_{FE} Classifications & Marking

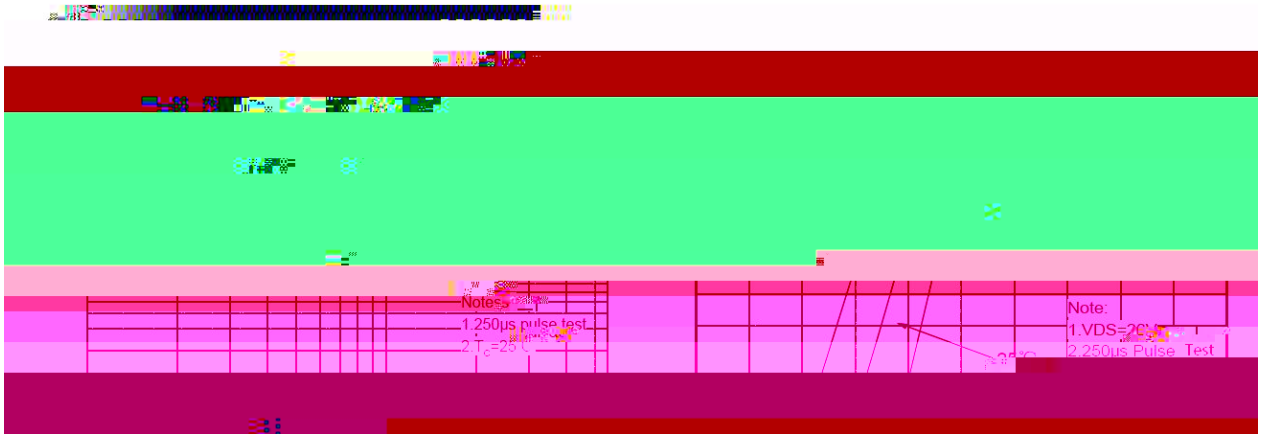
ﻫ ﻻ ب See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain Source Voltage	V_{DSS}	500	V
Gate-Source Voltage	V_{GSS}	±30	V
Drain Continuous- Current(Note 1)	I_D(Tc=25)	26	A

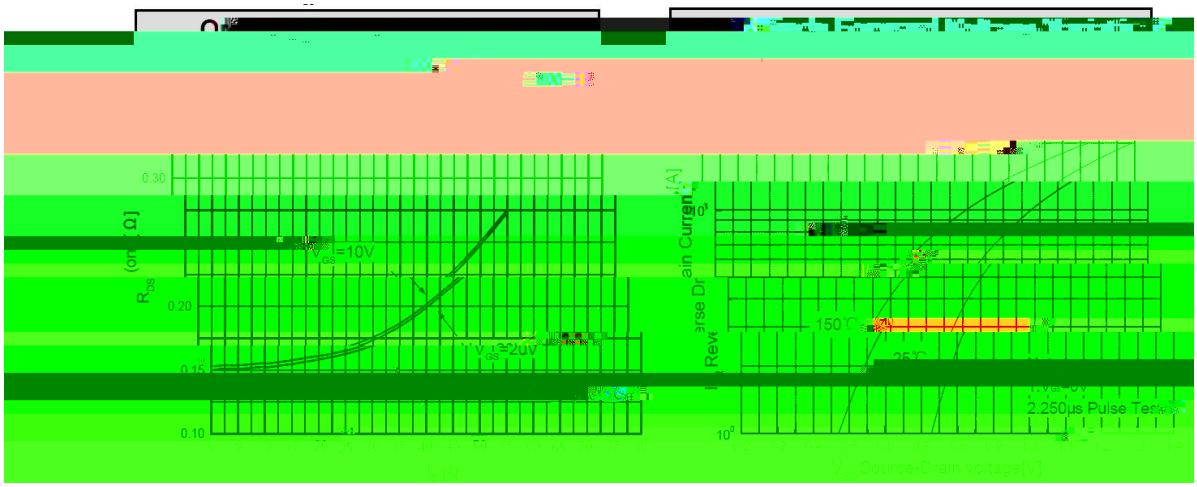
Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V	I_D=250μA	500			V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=500V	V_{GS}=0V			1	

⁼ ƎĄ´E ⅵ ƒ / Electrical Characteristic Curve

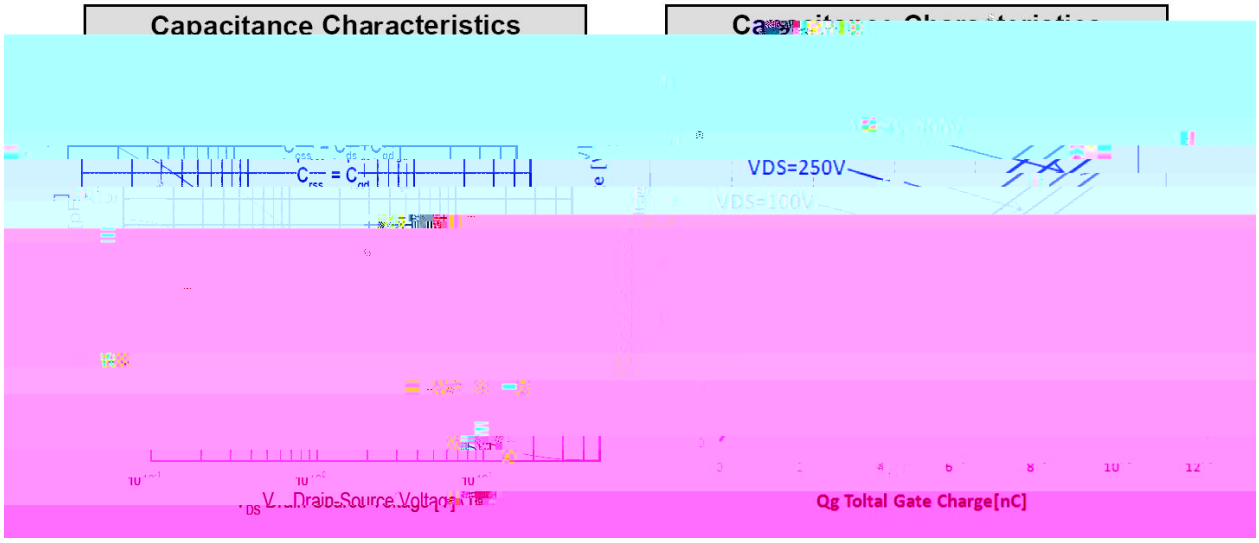
On-Region Characteristics



Transfer Characteristics

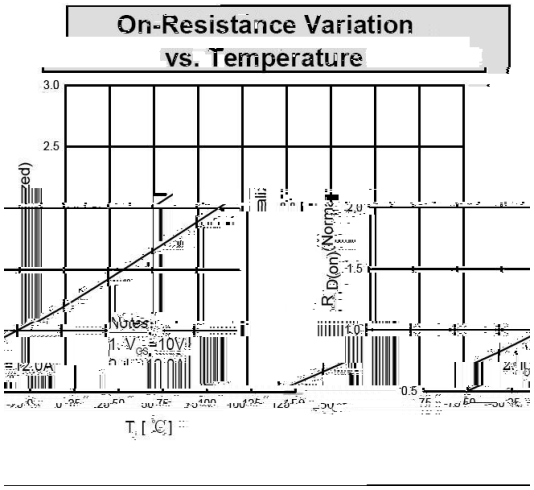


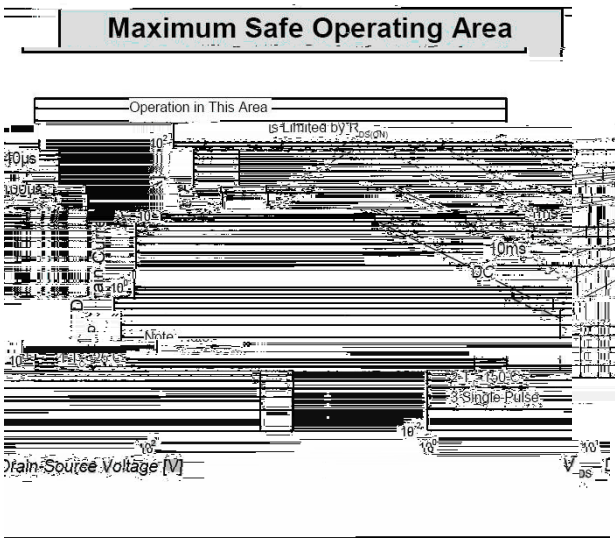
Capacitance Characteristics

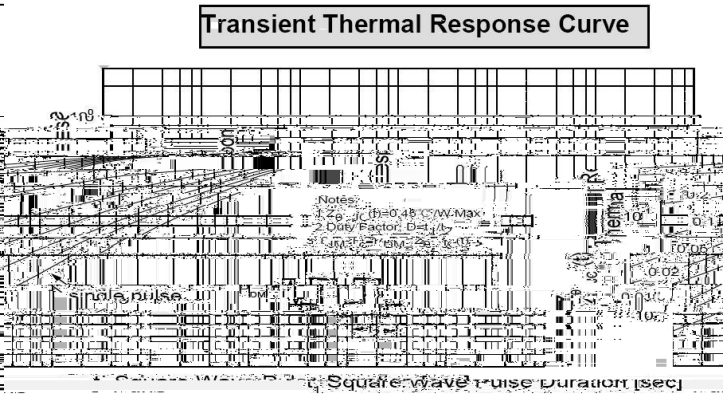


⸗ ⸝ ⸗ Ą / Electrical Characteristics(Ta=25 ⸝)

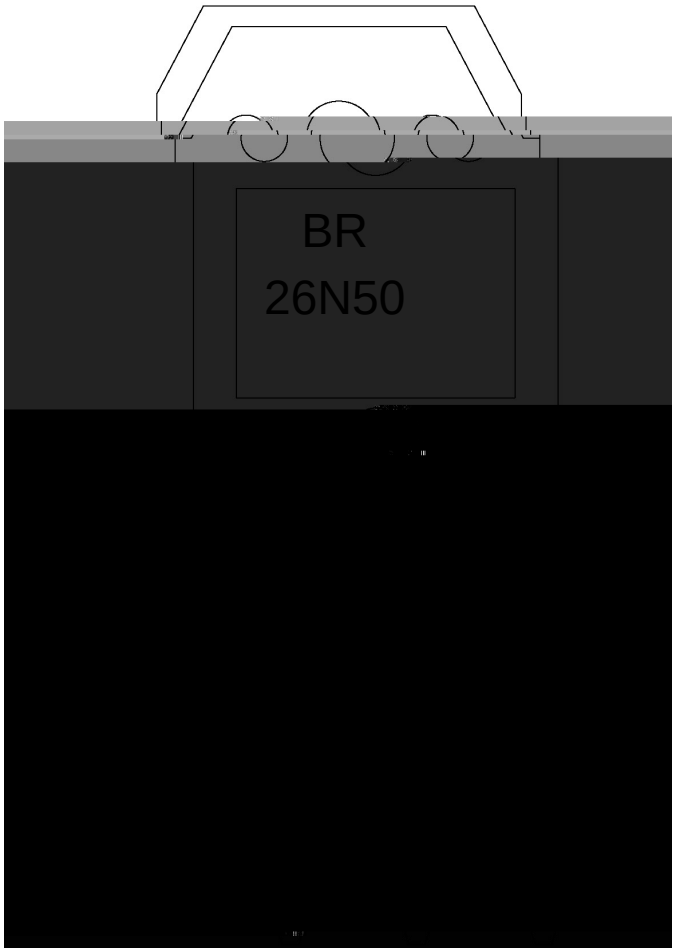



On-Resistance Variation
vs. Temperature


Maximum Safe Operating Area


Transient Thermal Response Curve

Ł ը Ն / Marking Instructions



ب

BR= И .

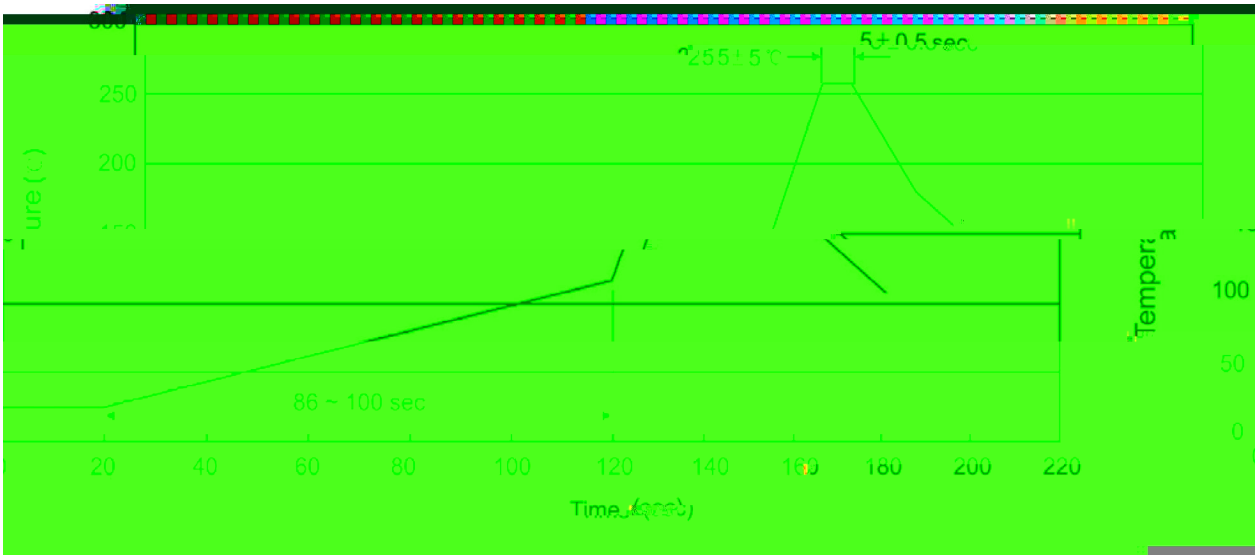
26N50 N .

**** N . ₿ N

Note:

BR:	Company Code.
26N50:	Product Type.
****:	Lot No. Code, code change with Lot No.

↓ ṣ ╗ ẘ ´E ⅵ ƒ (ᾠ ؤ) / Temperature Profile for Dip Soldering(Pb-Free)



ب

1 أ 25 150 ڑ 60 90sec;

2 255±5 ڑ ⅵ 5±0.5sec;

3 ⅵ ھ 2 10 /sec.

Note:

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

⅃ ü ˆ ˌ `Y Ţ / Resistance to Soldering Heat Test Conditions

270±5 ڑ 10±1 sec. Temp:270±5 Time:10±1 sec

ɒ ϙ L— / Packaging SPEC.

ˀ ⊢ / TUBE

Package Type	Units					Dimension		(unit mm^3)

ä ɤ ɒ ̈Ω / Notices